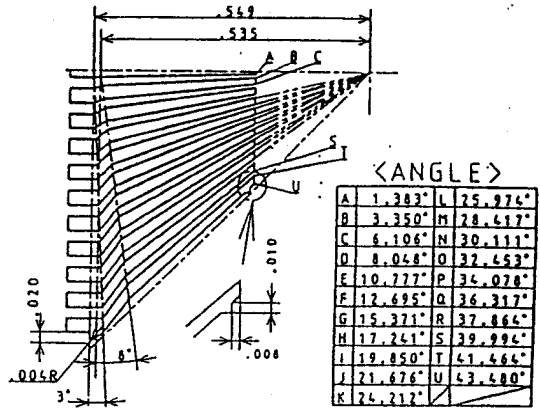
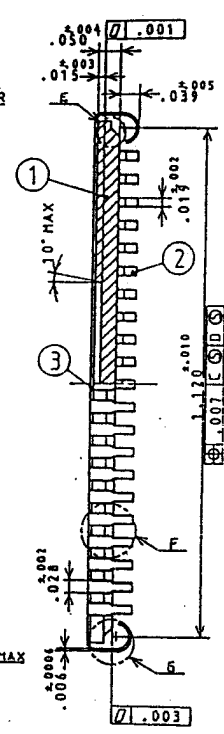
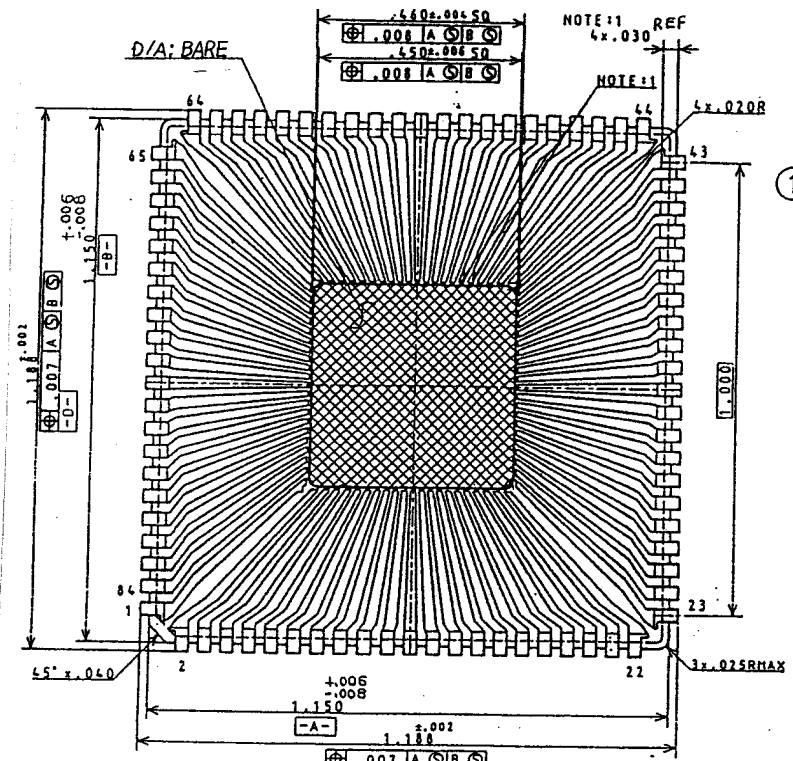
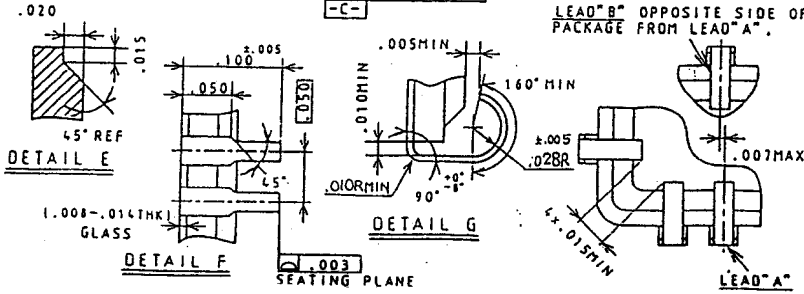


SSM P/N CQJ08406



- NOTES:
1. ALUMINUM BOND PADS 150μ" THK., ALUMINUM AREA FROM CERAMIC EDGE .030 REF.
 2. THERE WILL BE NO UNSUPPORTED BOND PADS GREATER THAN .010.
 3. ADJACENT BOND PADS MUST BE COPLANARITY WITHIN .006. TOTAL COPLANARITY NO GREATER THAN .010
 4. THERE WILL BE NO NICKS, CUT OR GLASS IN THE BEND RADIUS.
 5. ALTERA SPEC .04Q-00079 SHALL APPLY.
 6. B/F TRUE POSITION TOLERANCE ±.002.



3	SOLDER GLASS	CORNING 7583		C	RE DRAWING	6-21-90
2	LEAD FRAME	ALLOY 42		B	ADDED NOTE: 6	6-18-90
1	CERAMIC BASE	BLACK ALUMINA		A	RE DRAWING	6-15-90
				φ	NEW DRAWING	6-13-90
Item Name		Material	Description	Rev.	Description	Date
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1%		DRAWN M. Sawa		NMS TECHNICAL CERAMICS		
N. L. T. 2 DECIMALS. XX ± 01		CHECKED Z. Koch		HGX SPARK PLUG CO., LTD		
3 DECIMALS. XXX ± 005		APPROVED		TITLE		
CUSTOMER AL				84 LEAD "J" CERAMIC QUAD PKG		
DRW NO.		UNIT	INCH	DWG NO.		SIZE
		SCALE			L8420-7004B	A-3

